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FEE TRANSMITTAL

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TOTAL AMOUNT OF PAYMENT ($) 500.00

Complete If Known	
Application Number	10/767,281
Filing Date	30 January 2004
First Named Inventor	TAE-SUNG KIM *et. al.*
Examiner Name	WARREN, MATTHEW E.
Group/Art Unit	2815
Attorney Docket No.	P57002

METHOD OF PAYMENT (check one)

1. ■ **Payment Enclosed: (CHECK #51719)**
   ■ Check ❑ Credit Card ❑ Money Order
   ❑ Other

❑ Charge Any Additional Fee Required Under 37 C.F.R. §1.16 and 1.17.

❑ Applicant claims small entity status. See 37 CFR 1.27

2. ■ The Commissioner is hereby authorized to charge any deficiency and credit any over payments to:

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FEE CALCULATION

Fee Code	Fee ($)	Fee Code	Fee ($)	Fee Description	Fee Paid
				EXTENSION OF TIME FEES	
1251	120	2251	60	Extension for reply within first month	$
1252	450	2252	225	Extension for reply within second month	$
1253	1020	2253	510	Extension for reply within third month	$
1254	1590	2254	795	Extension for reply within fourth month	$
1255	2160	2255	1080	Extension for reply within fifth month	$
				APPEAL	
1401	500	2401	250	Notice of Appeal	$
1402	500	2402	250	Filing a brief in support of an appeal	$ 500.00
1403	1000	2403	500	Request for oral hearing	$
				CLAIMS	
1201	200	2201	100	Independent claims in excess of 3	$
1202	50	2202	25	claims in excess of 20	$
Other Fee (specify)					$
Other Fee (specify)					$
Other Fee (specify)					$

FEE CALCULATION

Fee Code	Fee ($)	Fee Code	Fee ($)	Fee Description	Fee Paid
				MISCELLANEOUS	
1801	$790	2801	$395	Request for continued examination (RCE)	$
1806	$180			Submission of an IDS	$
1814	$130	2814	$65	Statutory disclaimer	$
1501	$1,400	2501	$685	Utility issue fee (or reissue)	$
1504	$300	1504	300	Publication fee for early, voluntary, or normal publication	$
8021	$40			Recordation of assignment per property	$
				TRADEMARK	
6001/7001			$335	Application for registration, per class	$
6002/7002			$100	Amendment to Allege Use, per class	$
6003/7003			$100	Statement of Use, per class	$
6004/7004			$150	Request for six-month extension of time, per class	$
6205/7205			$100	§8 affidavit, per class	$
6208/7208			$200	§15 affidavit, per class	$
6201/7201			$400	Application for renewal, per class	$
6403/7403			$100	Ex parte appeal, per class	$
				PETITION	
1462			$400	Petitions to Director (Group I)	$
1463			$200	Petitions to Director (Group I)	$
1464			$130	Petitions to Director (Group II)	$
1452	$500	2452	$250	Petitions to revive unavoidably abandoned application	$
1453	$1500	2453	$750	Petitions to revive unintentionally abandoned application	$
				PATENT MAINTENANCE	
1551	$900	2551	$450	Due at 3.5 years	$
1552	$2300	2552	$1150	Due at 7.5 years	$
1553	$3800	2553	$1900	Due at 11.5 years	$
Other Fee (specify)					$
Other Fee (specify)					$
Other Fee (specify)					$

SUBTOTAL: LEFT COLUMN	$500.00	SUBTOTAL: RIGHT COLUMN	$0.00

SUBMITTED BY

Typed or Printed Name	Robert E. Bushnell, Esq.	Reg. Number	27,774
Signature	Robert E. Bushnell	Date: 22 November 2006	Deposit Account User ID:

REB/nm

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PATENT
P57002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE BOARD OF APPEALS AND INTERFERENCES

In re Application of:

Appeal No. _____

TAE-SUNG KIM *et al.*

Serial No.:	10/767,281	Examiner:	WARREN, MATTHEW E.
Filed:	30 January 2004	Art Unit:	2815

For: NOVEL CONDUCTIVE ELEMENTS FOR THIN FILM TRANSISTORS USED IN A FLAT PANEL DISPLAY

Attn: Board of Patent Appeals & Interferences

TRANSMITTAL OF APPELLANT'S BRIEF FEE

Mail Stop Appeal Brief-Patents
Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Sir:

Accompanying this transmittal is a check drawn to the Commissioner of Patents & Trademarks in the amount of $500.00 (Check #51719) for the filing an **Appeal Brief** in support of a Notice of Appeal filed on 27 September 2006. Should the check become lost, be deficient in payment, or should other fees be incurred, the Commissioner is authorized to charge Deposit Account No. 02-4943 of Applicant's undersigned attorney in the amount of such fees.

Respectfully submitted,

Robert E. Bushnell
Attorney for Applicant
Reg. No.: 27,774

1522 "K" Street, N.W., Suite 300
Washington, D.C. 20005
Area Code: 202-408-9040

Folio: P57002
Date: 11/22/06
I.D.: REB/nm

PATENT
P57002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE BOARD OF APPEALS AND INTERFERENCES

In re Application of:

Appeal No. _____

TAE-SUNG KIM *et al.*

Serial No.:	10/767,281	Examiner:	WARREN, MATTHEW E.
Filed:	30 January 2004	Art Unit:	2815

For: NOVEL CONDUCTIVE ELEMENTS FOR THIN FILM TRANSISTORS USED IN A FLAT PANEL DISPLAY

APPEAL BRIEF

Paper No. 22

Mail Stop Appeal Brief-Patents
Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to Appellants' Notice of Appeal filed on 27 September 2006, Appellants hereby appeal to the Board of Patent Appeals and Interferences from the rejection of claims 1, 2, 4-9, 11-15, 17-19, and 21-14 as set forth in the third Office action mailed on 28 July 2006 (Paper No. 20060722).

Folio: P57002
Date: 11/22/06
I.D.: REB/HMZ/kf

I. REAL PARTY IN INTEREST

Pursuant to 37 CFR §41.37(c)(1)(as amended), the real party in interest is:

SAMSUNG SDI CO., LTD.,
575, Shin-dong
Yeongtong-gu, Suwon-si, Gyeonggi-do
Republic of KOREA

as evidenced by the Assignment executed by the inventors on the 26th of January 2004 and recorded by the U.S. Patent and Trademark Office on the 30th of January 2004 at Reel 014944, Frame 0876.

II. RELATED APPEALS AND INTERFERENCES

There are no other appeals and no interferences known to Appellant, Appellant's legal representatives or the assignee which will directly affect, be directly affected by, or have a bearing on the Board's decision in the pending appeal.

III. STATUS OF CLAIMS

Claims 3, 10, 16, and 20 have been canceled. All remaining pending claims 1, 2, 4-9, 11-15, 17-19, and 21-24 are on appeal.

IV. STATUS OF AMENDMENTS

An Amendment After Final was submitted to the US Patent and Trademark Office on April 13, 2006. The Amendment After Final was entered as requested in the Request for Continued Examination (RCE) on May 15, 2006.

V. SUMMARY OF CLAIMED SUBJECT MATTER

The present invention relates to four separate features as evidenced by the four independent claims and their respective dependent claims.

Namely, independent claim 1 and dependent claims 2 and 4-7 recite a thin film transistor. Independent claim 8 and dependent claims 9 and 11-13 recite a flat panel display. Independent claim 14 and dependent claims 15 and 17-19 recite a Thin Film Transistor (TFT). Lastly, independent claim 21 and dependent claims 22-24 recites a process for making a flat panel display.

With regard to the thin film transistor, the specific features thereof are discussed in paragraphs [0042]-[0046] and illustrated in Figs. 2 and 7-10.

With regard to the flat panel display, the specific features thereof are discussed in paragraphs [0026]-[0039] and illustrated in Figs. 1-4.

With regard to the TFT, the specific features thereof are also discussed in paragraphs [0042]-[0046] and illustrated in Figs. 2 and 7-10.

Lastly, with regard to the process for making a flat panel display, the specific features thereof are discussed in paragraphs [0042]-[0051].

VI. GROUNDS OF REJECTION TO BE REVIEWED ON APPEAL

The present claims have been rejected under 35 U.S.C. §103 as obvious over Ohtani *et al.*

(U.S. Patent No. 6,271,543) in view of Maeda (U.S. Patent No. 5,278,099) for the reasons stated on pages 2-7 of the Office Action mailed on 28 July 2006.

In more detail, with regard to claims 1 and 14, the Examiner alleges that Ohtani shows all of the elements of the claims except the aluminum layer being an aluminum alloy and a diffusion prevention layer interposed between the aluminum alloy layer and each of the pair of titanium layers. The Examiner further alleges that Maeda teaches the features deficient in Ohtani.

With regard to claims 2 and 15, the Examiner argues that Maeda teaches the recited features of the claims except for the specific weight percentage of the element in the alloy. The Examiner then argues that the specific weight percentage would be obvious to one skilled in the art.

With regard to claim 4, the Examiner argues that Maeda teaches that each diffusion prevention layer is made of titanium nitrite.

With regard to claims 5 and 6, the Examiner argues that while the references do not teach the thickness of the titanium nitride or the percentage of nitrogen in the titanium nitride being within the desired range, such features be obvious to one skilled in the art.

With regard to claims 7 and 19, the Examiner argues that Maeda discloses that the aluminum electrode is an alloy containing silicon and is therefore absent of pure aluminum.

With regard to claims 17 and 18, the Examiner argues that a "product by process" claim limitation is directed to the product per se, no matter how actually made.

With regard to claims 8 and 21, the Examiner argues that while Ohtani does not show the complete active-matrix feature recited in the claims, such a recitation is well-known. The Examiner further argues that Ohtani shows all of the elements of the claims except for the alloy layer being an aluminum alloy and a diffusion prevention layer interposed between the aluminum alloy layer and each of the pair of titanium layers. The Examiner then argues that Maeda teaches the features deficient in Ohtani.

With regard to claims 9 and 22, the Examiner argues that Maeda teaches the recited features of the claims except for the specific weight percentage of the elements in the alloy. The Examiner then argues that the specific weight percentage would be obvious to one skilled in the art.

With regard to claims 11 and 23, the Examiner argues that Maeda discloses each diffusion prevention layer being made of titanium nitride.

Lastly, with regard to claims 12 and 24, the Examiner argues that while the references do not teach the thickness of the titanium nitride or the percentage of nitrogen in the titanium nitride being within the desired range, such features be obvious to one skilled in the art.

VII. ARGUMENT

The Examiner has correctly noted that Ohtani et al. teaches a three-layer laminated structure of titanium/aluminum/titanium for the source wiring line and drain electrode of Ohtani et al. (See lines 10-13 of column 7 of Ohtani et al.)

However, lines 59-62 of column 6 of Ohtani et al. indicate that a film of aluminum or a material mainly containing aluminum is formed and patterned to form the gate wiring line of Ohtani et al.

Accordingly, it is submitted that Ohtani et al. teaches away from a three-layer laminated structure of titanium/aluminum alloy/titanium in that there is an inference that Ohtani's failure to indicate that an aluminum alloy can be used for the source wiring line and drain electrode after previously indicating that an aluminum or aluminum alloy can be used for the gate wiring line infers that Ohtani **only** considered pure aluminum for the source wiring line and drain electrode.

Furthermore, while Maeda indicates in lines 22-31 of column 4 thereof that the layer 36 is not limited to pure aluminum but rather can be an aluminum alloy, Maeda indicates in lines a 62-64 of column 3 thereof that since the TiN layer 34 has a thickness sufficient to prevent the growth of alloy spikes, aluminum layer 36 need not contain silicon. Accordingly, there is an inference that the use of a TiN layer precludes the need for an aluminum alloy layer and allows the layer 36 to be pure aluminum.

The independent claims recite that one of the source electrode and drain electrode

comprises an aluminum alloy layer disposed between a pair of titanium layers. That is, the recitation that the gate electrode comprises an aluminum alloy layer disposed between a pair of titanium layers has been deleted.

Ohtani et al., on the other hand, refers to a titanium/aluminum/titanium structure only for the source and drain electrodes and refers to an aluminum alloy only for the gate electrodes. Thus, the source and drain electrodes of Ohtani et al. do not correspond to the recited source and drain electrodes of the independent claims.

In responding to the above-noted arguments contained in the previously submitted September 27, 2005 Amendment and April 13, 2006 Amendment After Final, the Examiner **admits** on page 7 of the July 28, 2006 Office Action that "Ohtani . . . does not specifically disclose that the Al layer is an aluminum alloy layer." The Examiner then continues: "The gate electrode having the same Ti/Al/Ti structure is cited in Ohtani as using an Al layer. Therefore, it is **assumed** that the source and drain electrodes of Ohtani **may** also comprise an Al alloy." (Emphasis added)

Appellants strongly disagree with the Examiner's unsupported assumptions. That is, there is no teaching or suggestion or incentive in Ohtani to fabricate the source and drain electrodes with the same material used to fabricate the gate electrode. In fact, the source and drain electrodes are oftentimes of a different material than that used for the gate electrode.

Furthermore, even assuming arguendo that the source and drain electrodes are of the same material as the gate electrode, this does not result in the conclusion that it would be obvious to

fabricate the source and drain electrodes of the same material as the gate electrode.

Stated simply, it is settled patent law that merely because one **can** modify a subject device in a reference to produce a device which purportedly meets the recited limitations of a rejected claim does **not** mean that it would be obvious to do so. The Examiner has used the wrong criterion to argue the obviousness of modifying a reference.

Furthermore, the Examiner argues that Maeda was cited to cure the deficiencies of Ohtani in that Maeda discloses that an electrode **can** comprise an alloy of aluminum. Again, the Examiner has used the wrong criterion to argue the obviousness of modifying a reference.

As to the recited specific weight percentage of the element in the alloy and the thickness of the titanium nitride layer or the percentage of nitrogen within the desired range, the Examiner has made an unsupported statement that these recited features would be obvious to one skilled in the art. Yet, the Examiner admits that neither Ohtani nor Maeda teaches or suggests these recited features, nor has the Examiner submitted secondary references which teach or suggest these recited features.

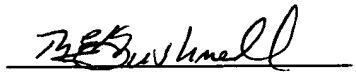
As to the rejection of claim 18, even disregarding the recited process limitation, claim 18 recites that the semiconductor of layer forming a conductive channel between the source electrode and drain electrode upon application of a voltage to the gate electrode does not appear to have been considered by the Examiner.

With regard to the specific comments by the Examiner in rejecting claims 8 and 21, the Examiner admits that Ohtani does not show the complete active-matrix having a second plurality of thin-film transistors, wherein the first drain electrodes of the first plurality of thin-film transistors are electrically connected to gate electrodes of the second plurality of thin-film transistors. The Examiner then argues that such a recitation is that of a well-known routing scheme and then cites the Yamazaki publication as teaching such a feature.

However, the Examiner has only rejected claims 8 and 21 as obvious over the combination of Ohtani and Maeda and the inclusion of the citation of the Yamazaki publication is therefore improper.

In conclusion, it is submitted that it would not be obvious to combine the features of Ohtani and Maeda in the fashion noted by the Examiner such that it is submitted that all of the claims now on appeal are patentable over the combination of Ohtani and Maeda and should now be in a condition suitable for allowance.

Respectfully submitted,



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Date: 11/22/06
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VIII. APPENDIX

CLAIMS UNDER APPEAL (Claims 1, 2, 4-9, 11-15, 17-19, 21-24)

1. (Previously Presented) A thin film transistor, comprising a source electrode, a drain electrode, a gate electrode and a semiconductor layer, wherein one of the source electrode and drain electrode comprises an aluminum alloy layer disposed between a pair of titanium layers, wherein a diffusion prevention layer is interposed between the aluminum alloy layer and each of the pair of titanium layers, and wherein the aluminum alloy layer comprises at least one element selected from a group consisting of silicon, copper, neodymium, platinum and nickel.

2. (Original) The thin film transistor of claim 1, wherein the aluminum alloy layer comprises about 0.1 to 5 wt% of at least one element selected from a group consisting of silicon, copper, neodymium, platinum and nickel.

4. (Previously Presented) The thin film transistor of claim 1, wherein each diffusion prevention layer is made of titanium nitride.

5. (Previously Presented) The thin film transistor of claim 4, wherein each titanium nitride layer has a thickness between 100 and 500Å.

6. (Previously Presented) The thin film transistor of claim 4, wherein each titanium nitride layer contains 5 to 85 wt% of nitrogen.

7. (Original) The thin film transistor of claim 1, each electrode being absent of pure

aluminum.

8. (Previously Presented) A flat panel display, comprising:

a substrate;

a first plurality of thin film transistors formed on a surface of the substrate, the first plurality of thin film transistors comprising first source electrodes, first drain electrodes, first gate electrodes, and semiconductor layers;

a plurality of first conductive lines electrically connected to the first source electrodes; and

a plurality of second conductive lines electrically connected to the first gate electrodes;

a second plurality of thin film transistors, wherein the first drain electrodes of the first plurality of thin film transistors are electrically connected to gate electrodes of the second plurality of thin film transistors, wherein one of the first source electrodes, the first drain electrodes, the plurality of first conductive lines, and the plurality of second conductive lines comprises an aluminum alloy layer and a titanium layer formed on both surfaces of the aluminum alloy layer, wherein a diffusion prevention layer is interposed between the aluminum alloy layer and the titanium layers, and wherein the aluminum alloy layer comprises at least one element selected from a group consisting of silicon, copper, neodymium, platinum and nickel.

9. (Original) The flat panel display of claim 8, wherein the aluminum alloy layer comprises about 0.1 to 5 wt% of at least one element selected from the group consisting of silicon, copper, neodymium, platinum and nickel.

11. (Previously Presented) The flat panel display of claim 8, wherein each diffusion prevention layer is made of titanium nitride.

12. (Previously Presented) The flat panel display of claim 11, wherein each titanium nitride layer has a thickness between 100 to 500Å.

13. (Original) The flat panel display of claim 11, wherein each titanium nitride layer contains 5 to 85 wt% of nitrogen.

14. (Previously Presented) A TFT, comprising:

a source electrode, a gate electrode and a drain electrode; and

a semiconductor layer between the source electrode and the drain electrode, wherein one of said source electrode and said drain electrode contain an aluminum alloy layer bounded by a pair of titanium layers and not a pure aluminum layer, wherein said source electrode and said drain electrode each comprising a TiN diffusion prevention layer between the aluminum alloy layer and each titanium layer, and wherein the aluminum alloy layer comprises at least one element selected from a group consisting of silicon, copper, neodymium, platinum and nickel.

15. (Original) The TFT of claim 14, wherein the aluminum alloy layer comprises about 0.1 to 5 wt% of at least one element selected from the group consisting of silicon, copper, neodymium, platinum and nickel.

17. (Original) The TFT of claim 14, said semiconductor layer being absent of aluminum after said TFT is subjected to a heat treatment of at least 300 degrees Celsius.

18. (Original) The TFT of claim 14, said semiconductor layer being primarily made of silicon and said semiconductive layer forming a conductive channel between said source electrode and said drain electrode upon application of a voltage to the gate electrode after said TFT is exposed to heat of at least 300 degrees Celsius.

19. (Original) The TFT of claim 14, said source electrode and said drain electrode both being formed of aluminum alloy and both being absent pure aluminum.

21. (Previously Presented) A process for making a flat panel display, comprising:

forming a first plurality of thin film transistors formed on a surface of a substrate, the first plurality of thin film transistors comprising first source electrodes, first drain electrodes, first gate electrodes, and semiconductor layers;

electrically connecting a plurality of first conductive lines to the first source electrodes;

electrically connecting a plurality of second conductive lines to the first gate electrodes; and

forming a second plurality of thin film transistors, electrically connecting the first drain electrodes of the first plurality of thin film transistors to gate electrodes of the second plurality of thin film transistors, wherein one of the first source electrodes, the first drain electrodes, the plurality of first conductive lines, and the plurality of second conductive lines comprises an aluminum alloy layer and a titanium layer formed on both surfaces of the aluminum alloy layer, and interposing a diffusion prevention layer between the aluminum alloy layer and the titanium layers, and wherein the aluminum alloy layer comprises at least one element selected from a group consisting of silicon, copper, neodymium, platinum and nickel.

22. (Previously Presented) The process of claim 21, comprised of making the aluminum alloy layer from an aluminum alloy comprising about 0.1 to 5 wt% of at least one element selected from the group consisting of silicon, copper, neodymium, platinum and nickel.

23. (Previously Presented) The process of claim 21, comprised of making the diffusion prevention layers of titanium nitride.

24. (Previously Presented) The process of claim 23, comprised of making the titanium nitride layers with a thickness between 100 to 500Å.

IX. EVIDENCE APPENDIX

None.

X. RELATED PROCEEDINGS APPENDIX

None.